

Customer Information Notification

Issue Date: 11-Nov-2016 Effective Date: 09-Feb-2017

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online

2016100101



Management Summary

Device orientation in carrier tape was specified in the datasheet as Q2/T3 when it should be Q4/T2. The product datasheet has been updated to reflect the Q4/T2 orientation.

Change Category

[] Wafer Fab	[] Assembly	[] Product Marking	[] Test	[] Design
Process	Process		Location	
[] Wafer Fab	[] Assembly	[] Mechanical Specification	[]Test Process	s [] Errata
Materials	Materials			
[] Wafer Fab	[] Assembly	[X]	[] Test	[] Electrical spec./Test
Location	Location	Packing/Shipping/Labeling	Equipment	coverage

SC18IS602BIPW Update To Reflect Correct Orientation in Carrier Tape

Information Notification

Device orientation in carrier tape was specified in the datasheet as Q2/T3 when it should be Q4/T2.

Why do we issue this Information Notification

To advise customers of the incorrect information in the datasheet.

Identification of Affected Products

Product identification does not change

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

A new datasheet will be issued

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Dennis Dill

Position Quality Engineer e-mail address dennis.dill@nxp.com

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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